

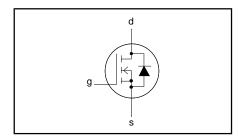
N-channel TrenchMOSTM transistor

PSMN030-150B

FEATURES

- 'Trench' technology
- Very low on-state resistance
- Fast switching
- Low thermal resistance

SYMBOL



QUICK REFERENCE DATA

$$V_{DSS}$$
 = 150 V I_{D} = 55.5 A $R_{DS(ON)} \le 30 \text{ m}\Omega$

GENERAL DESCRIPTION

SiliconMAX products use the latest Philips Trench technology to achieve the lowest possible on-state resistance in each package at each voltage rating.

Applications:-

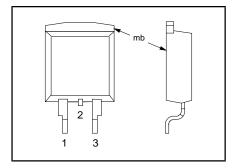
- d.c. to d.c. converters
- switched mode power supplies

The PSMN030-150B is supplied in the SOT404 (D²PAK) Surface mounted package.

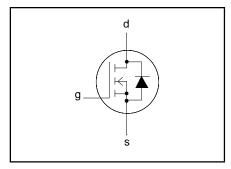
PINNING - SOT404

PIN	DESCRIPTION		
1	gate		
2	drain (no connection possible)		
3	source		
mb	drain		

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{\rm DSS}$	Drain-source voltage	T _i = 25 °C to 175°C	-	150	V
V_{DGR}	Drain-gate voltage	$T_i = 25 ^{\circ}\text{C}$ to 175 $^{\circ}\text{C}$; $R_{GS} = 20 \text{k}\Omega$	-	150	V
V _{GS}	Gate-source voltage	,	-	± 20	V
I _D	Continuous drain current	$T_{mb} = 25 ^{\circ}C$	-	55.5	Α
		$T_{mb} = 100 ^{\circ}C$	-	39	Α
I _{DM}	Pulsed drain current	$T_{mb} = 25 ^{\circ}C$	-	222	Α
P_{D}	Total power dissipation	$T_{mb} = 25 ^{\circ}C$	-	250	W
T_{j} , T_{stg}	Operating junction and storage temperature		- 55	175	°C

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AVALANCHE ENERGY LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
7.0	energy	Unclamped inductive load, $I_{AS} = 35 \text{ A}$; $t_p = 100 \mu\text{s}$; $T_j \text{ prior to avalanche} = 25 ^{\circ}\text{C}$; $V_{DD} \le 50 \text{ V}$; $R_{GS} = 50 \Omega$; $V_{GS} = 10 \text{ V}$;	-	300	mJ
7.0	Non-repetitive avalanche current		-	35	Α

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
R _{th j-mb}	Thermal resistance junction		-	0.6	K/W
R _{th j-a}	to mounting base Thermal resistance junction to ambient	Minimum footprint, FR4 board	50	-	K/W

ELECTRICAL CHARACTERISTICS

T_i= 25°C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 0.25 \text{ mA};$ $T_i = -55 ^{\circ}\text{C}$	150 133	-	-	V
$V_{GS(TO)}$	Gate threshold voltage	$V_{DS} = V_{GS}$; $I_D = 1 \text{ mA}$	2.0	3.0	4.0	V
	-	T _j = 175°C T _i = -55°C	1.0	-	-	V
R _{DS(ON)}	Drain-source on-state	$V_{GS} = 10 \text{ V}; I_{D} = 25 \text{ A}$	-	- 24	6 30	V mΩ
I _{GSS}	resistance Gate source leakage current	$V_{GS} = \pm 10 \text{ V}; V_{DS} = 0 \text{ V}$	-	2	81 100	mΩ nA
I _{DSS}	Zero gate voltage drain	$V_{DS} = 150 \text{ V}; V_{GS} = 0 \text{ V};$	-	0.05	10	μΑ
	current	$T_j = 175^{\circ}C$	-	-	500	μA
Q _{g(tot)}	Total gate charge	$I_D = 55.5 \text{ A}; V_{DD} = 120 \text{ V}; V_{GS} = 10 \text{ V}$	-	98	-	nC
Q_{gs}	Gate-source charge		-	16	-	nC
Q_{gd}	Gate-drain (Miller) charge		-	38	50	nC
t _{d on}	Turn-on delay time	$V_{DD} = 75 \text{ V}; R_D = 1.5 \Omega;$	-	18	-	ns
t _r	Turn-on rise time	$V_{GS} = 10 \text{ V}; R_G = 5.6 \Omega$ Resistive load	-	71 97	-	ns
$t_{d \; off} \ t_{f}$	Turn-off delay time Turn-off fall time	Resistive load	-	76	-	ns ns
L _d	Internal drain inductance	Measured from tab to centre of die	-	3.5	-	nH
Ls	Internal source inductance	Measured from source lead to source bond pad	-	7.5	-	nΗ
C _{iss}	Input capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V}; f = 1 \text{ MHz}$	-	3680	-	рF
Coss	Output capacitance	, 55 , 56 ,	-	470	-	pF
C _{rss}	Feedback capacitance		-	220	-	pF

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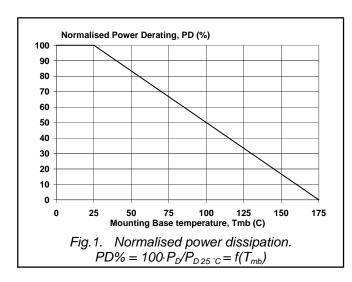
REVERSE DIODE LIMITING VALUES AND CHARACTERISTICS

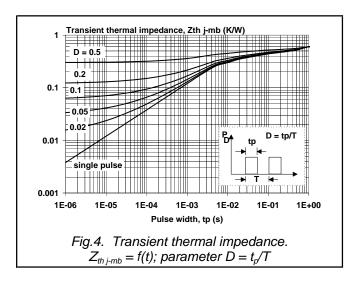
T_i = 25°C unless otherwise specified

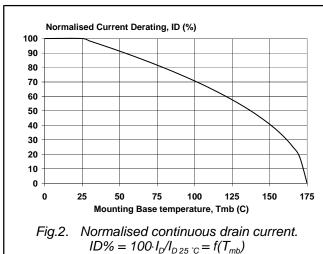
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Is	Continuous source current (body diode)		-	-	55.5	Α
I _{SM}	Pulsed source current (body diode)		-	-	222	Α
V_{SD}	Diode forward voltage	$I_F = 25 \text{ A}; V_{GS} = 0 \text{ V}$	-	0.85	1.2	V
t _{rr} Q _{rr}	Reverse recovery time Reverse recovery charge	$I_F = 20 \text{ A}; -dI_F/dt = 100 \text{ A}/\mu\text{s}; \ V_{GS} = 0 \text{ V}; V_R = 30 \text{ V}$	1 1	109 610	-	ns nC

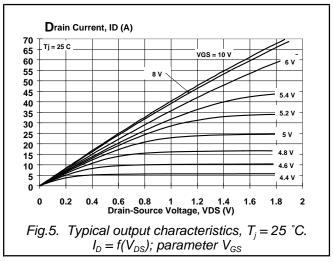
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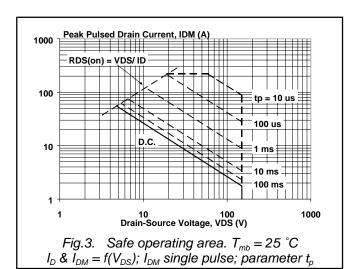
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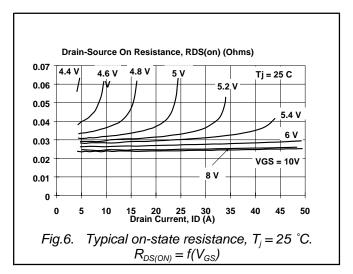






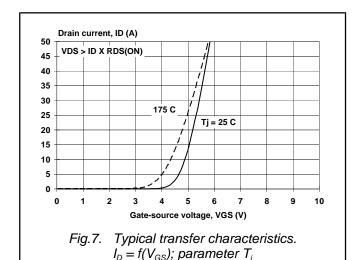






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Threshold Voltage, VGS(TO) (V)

4.5

4

3.5

3

2.5

2

1.5

1

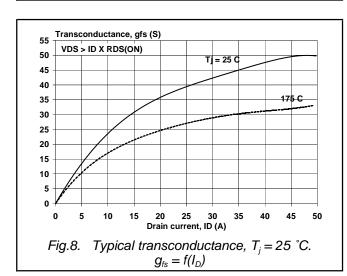
0.5

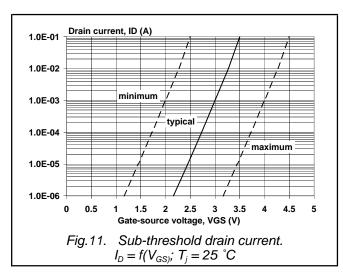
0

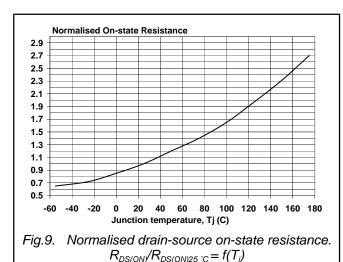
-60 -40 -20 0 20 40 60 80 100 120 140 160 180

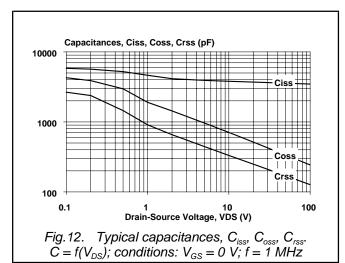
Junction Temperature, Tj (C)

Fig. 10. Gate threshold voltage. $V_{GS(TO)} = f(T_j)$; conditions: $I_D = 1$ mA; $V_{DS} = V_{GS}$









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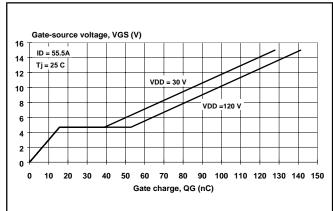
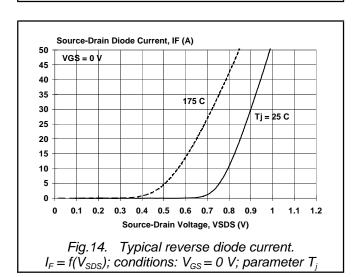


Fig.13. Typical turn-on gate-charge characteristics $V_{GS} = f(Q_G)$



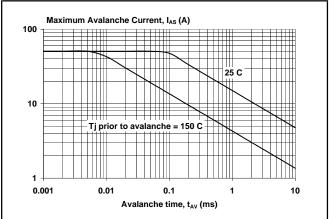


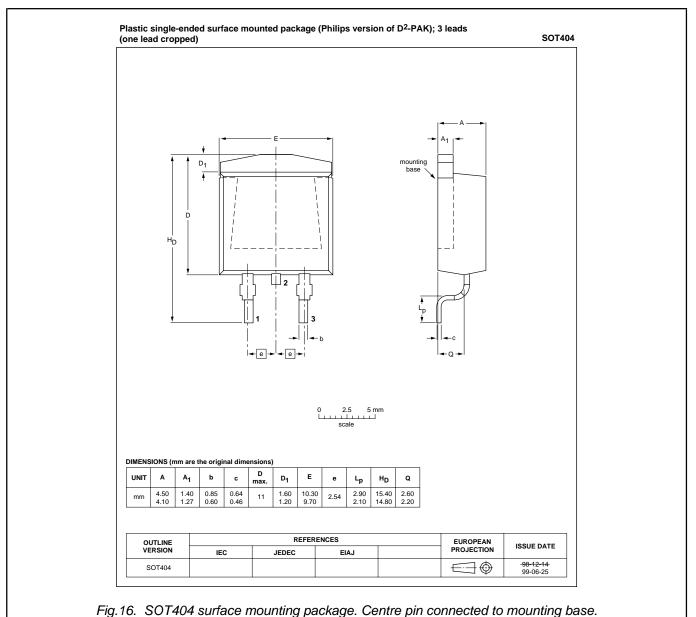
Fig.15. Maximum permissible non-repetitive avalanche current (I_{AS}) versus avalanche time (t_{AV}); unclamped inductive load

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MECHANICAL DATA



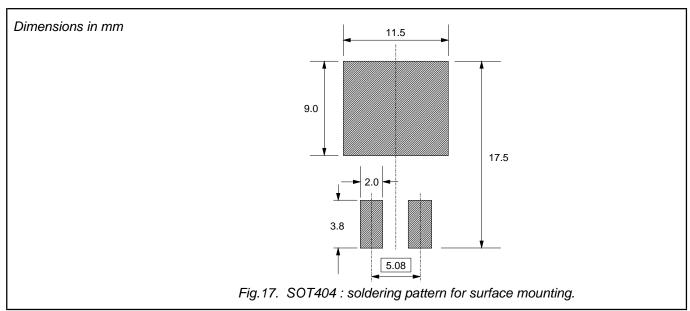
Notes

- 1. This product is supplied in anti-static packaging. The gate-source input must be protected against static discharge during transport or handling.
- 2. Refer to SMD Footprint Design and Soldering Guidelines, Data Handbook SC18.
- 3. Epoxy meets UL94 V0 at 1/8".

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MOUNTING INSTRUCTIONS



DEFINITIONS

Data sheet status				
Objective specification This data sheet contains target or goal specifications for product development.				
Preliminary specification This data sheet contains preliminary data; supplementary data may be published la				
Product specification This data sheet contains final product specifications.				
Limiting values				

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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